

TECHNICAL DATA VT02 400nm RADFET in 8L Side Braze Ceramic package For doses between 1cGy (1rad) and 1kGy (100krad)

Table 1: VT02 pin-out description.

Description

Source/bulk (common)

Drain of R1

Gate of R1

Not connected

Gate of R2

Drain of R2

Diode Anode¹

Not connected

VT02 Description and Pin-Out

The VT02 is Varadis 400nm RADFET chip packaged in 8 lead ceramic side braze package. The part consists of two identical RADFETs, R1 and R2, and a diode (see Figure 1 and Table 1). The RADFETs' gate oxide thickness is 400nm and W/L is 300μ m/50 μ m. The RADFETs have individual gate and drain terminals, while the source and bulk are common and connected together; this is also the diode bulk contact.

Pin

Number

1

2

3

4

5

6

7

8



Figure 1: VT02 pin-out drawing.

Maximum Ratings

Maximum ratings of the VT02 RADFET are given in Table 2.

Table 2: Maximum ratings of the VT02. Measured at room temperature.

Characteristics	Symbol	Specification	Unit	Remarks
Drain-Source Voltage	VDS	-25	V	
Gate-Source Voltage	Vgs	±50	V	
Drain-Gate Voltage	Vdg	±50	V	
Drain Current	lо	-1	mA	Continuous
Source Current	s	-1	mA	Continuous
Temperature Endurance Range	TER	-55 to +125	°C	
Maximum sensitivity	Smax	0.65	mV/cGy	

Modes of Operation

Irradiation Mode (Sense Mode)

 $^{^{1}\}ensuremath{\,{\rm More}}$ information about the purpose of the on-chip diode you can find in the notes section



In this mode of operation, it is recommended that all terminals of the RADFET are connected to ground. For alternative biasing options, contact the manufacturer.

Read-Out Mode (Accumulated Radiation Dose Read-Out)

The RADFET can be read at arbitrary intervals, depending on the application. The period between readings can be from seconds to days or even months. The circuit used to read out the RADFET (Reader Circuit - RC) is shown in Figure 2 with connection configuration in Table 3.



Terminal Bias			
S=B	Current is forced (RC_I) Voltage reading is taken (RC_V)		
G=D	0V (common)		

Table 3: Connections in Read-Out mode.

Figure 2: Reader Circuit (RC) configuration.

Current RC_I is forced into the RADFET, connected in RC configuration (Figure 2). The voltage at the source (RC_V) is measured; this voltage is called "RC threshold voltage". Typical I-V curves at different temperatures for un-irradiated device in this configuration are shown in Figure 3. In principle, any read-out current (RC_I) value above 5 μ A can be chosen if the value is kept unchanged after the start of radiation exposure. For best temperature compensation, the RC_I value of 10 μ A is recommended where the temperature influence is minimal.





The most important electrical parameter of un-irradiated RADFET is RC threshold voltage (RC_V). Specification for RC_V is given in Table 4. Results of RC_V measurements prior to

shipment are included in documentation that comes with ordered parts. Typically, the range of RC_V of delivered parts is significantly tighter than in the specification.

_	-	Test Circuit and	Limits			
Parameter	Symbol	Conditions	Min	Max	Unit	
RC Threshold Voltage	RC_V	Figure 2 and Table 3 RC_I = 10µA	0.8	3.0	V	

	100 10	c		14			
Table 4: S	pecification	for RC	threshold	voltage.	Measured	at room	temperature.

Calibration Data

The calibration curve for the RADFET shows evolution of ΔV (the change in RC threshold voltage with reference to its pre-irradiation value) with dose. Note that a specific calibration curve, obtained using the Co-60 source, is associated with each RADFET production batch. The calibration curve, together with analytical equation and fitting coefficients, will be provided with the supplied parts. For illustration, typical calibration curve is shown in Figure 4.



Figure 4: Typical calibration curve indicating change in RC_V during irradiation. Irradiation at room temperature with Co-60 gamma source, dose rate ~50 Gy/h (5 krad/h). Voltage measurements performed at room temperature using 0.2% duty cycle with all terminals grounded between measurements

Package Information

VT02 package specifications are given in Table 5, and package diagram in Figure 5.

 Table 5: VT02 package specifications.

0.254mm

7.62 ±0.2 mm

2.16mm

0.254mm



Description	Specification
Package Type	8-pin side braze ceramic package with kovar lid
Package Dimensions (L x W x H)	10.29mm x 7.87mm x 2.41mm (see Figure 5)



Recommended dimensions for solder pad layout are given Figure 6.



Figure 6: Recommended solder pad layout. Dimensions are inclusive of plating.

Handling

Our RADFETs undergo 100% electrical test and visual inspection immediately prior to shipment. Therefore, all parts should reach the customer in excellent condition. To ensure



that the RADFETs remain in this condition, please handle the parts as carefully as possible and observe standard precautions related to ESD sensitive devices.

Soldering

For our RADFETs we strongly recommend hand soldering onto printed circuit boards prior to exposure in radiation field. The temperature used in the soldering should be as low as possible using low-temperature melting point solder alloys. It is a good practice to solder the pins individually with 10sec break between pins, this will prevent overheating of the RADFET die and allow the heat generated from the soldering to dissipate.

It is important that the RADFET is the last component to be soldered onto a circuit board. If different soldering method is required, please contact us at <u>support@varadis.com</u>.

We usually calibrate our ceramic packaged components using test fixtures without soldering onto printed circuit boards. If soldering is required by the customer, please follow the above instructions.

Notes

We calibrate our standard products at room temperature using a Co-60 gamma-ray source. Irradiation is performed in a single event at the dose rate of ~50 Gy/hour (5 krad/hour) and includes the dose range from 1–1,000 Gy (100 rad – 100 krad). The voltage measurements are recorded using a 250ms width current pulse. There is a 120second period between measurements when all terminals are grounded – this equals a measurement duty cycle of approximately 0.2%.

Customers whose requirements include conditions significantly different from the above should contact <u>support@varadis.com</u> to discuss the optimum way to implement the RADFETs for their specific applications.

The VT02 has a large dynamic range, from 1 cGy (1 rad) to 1 kGy (100 krad) and beyond (with additional calibration).

While the supplied calibration curve covers doses from 1–1,000 Gy, other measurements at room temperature show that lower doses, down to 1 cGy, can be detected. The lower the minimum dose required by the customer, the more accurate must be the RADFET temperature compensation and read-out electronics. Please contact <u>support@varadis.com</u> for further details if your application includes lower dose range.

Regarding the high end of the dose range, VT02 can measure doses even higher than 1 kGy (100 krad). However, the sensitivity decreases with dose and it depends on the actual application requirements whether this sensitivity loss is acceptable. As VT02 comes calibrated up to 1 kGy (100 krad), additional calibration is needed for measurements beyond this limit.

The on-chip diode is connected between pin 7 (anode) and pin 1 (cathode). The diode is not sensitive to ionizing radiation in the way the RADFETs are. The diode can be used as an indicator of the chip temperature during irradiation (sense mode) only.



During RADFET irradiation (sense mode) the diode can be forward biased by forcing positive current into pin1 and the diode voltage obtained at the same pin. It is recommended that after diode forward bias, pin1 is connected back to the ground or remain floating.

During RADFET read-out mode (accumulated radiation dose read-out) the diode <u>must not</u> be forward biased as it will influence the RADFET readout voltage and disturb the measurement.

For diode response over a temperature range, and other queries related to this document please contact <u>support@varadis.com</u>.